

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L13	125	34/585	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:23
L12	199	34/576	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:23
L11	900	34/58	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:23
L10	1614	retaining with rotat\$3 same (wafer or substrate or semi \$1conductor or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:22
L9	662	retainer with rotat\$3 same (wafer or substrate or semi \$1conductor or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:22
L8	5154	vertically with rotat\$3 same (wafer or substrate or semi \$1conductor or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:01
L7	11369	vertical with rotat\$3 same (wafer or substrate or semi \$1conductor or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 11:00
L6	118	(disk or disc).ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash \$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) and (wafer or substrate or semi \$1conductor or semiconductor) same (support\$3 or hold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/25 10:59

L5	676	perimeter with rotat\$3 same (wafer or substrate or semi\$1conductor or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 10:59
L4	18108	(side) with rotat\$3 same (wafer or substrate or semi\$1conductor or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 10:58
L3	845	134/199	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 10:57
L2	456	134/149	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 10:51
L1	39329	(substrate or wafer or semi\$1conductor or semiconductor) and clean\$3 and rotat\$3 and (spray\$3 or nozzle)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/25 10:36
S84	817	(wafer or substrate or semi\$1conductor or semiconductor).ab. same (rotat\$3 or spin \$3 or spinning or turn \$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) same (side or perpendicular or lateral or horizontal\$3) and (wafer or substrate or semi\$1conductor or semiconductor) with (support\$3 or hold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:48
S83	1904	(wafer or substrate or semi\$1conductor or semiconductor).ab. same (rotat\$3 or spin \$3 or spinning or turn \$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) and (wafer or substrate or semi\$1conductor or semiconductor) same (support\$3 or hold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:47

S82	5	yang adj reg.in.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 17:43
S81	1053	(substrate or wafer or semi\$1conductor or semiconductor) same clean\$3 same rotat\$3 same (spray\$3 or nozzle) and seal\$3	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 17:21
S80	101	S79 and (semi \$conductor or wafer or semiconductor or workpiece).clm. and (wash\$3 or spray\$3 or clean\$3 or jet\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 17:16
S79	845	134/199	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 17:15
S78	1378	134/198	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 17:15
S77	12	("2907595" "3093282" "3531131" "3823950" "4060250" "4098515" "4337951" "4815747" "5435075").PN. OR ("7347214").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 17:13
S76	455	134/148	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:13
S75	319	S63 and "134".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:10
S74	229	134/84	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:10
S73	151	134/85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:10
S72	596	134/137	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:10
S71	377	134/151	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:10

S70	2	"6174011".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 17:09
S69	3247	(wash\$3 or clean\$3 or spray\$3 or jet\$4) same (circumferential with (wall or surface or retain\$3 or hold\$3)) same (semiconductor or semi\$conductor or wafer or disc or disk)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:11
S68	35049	(circumferential with (wall or surface or retain\$3 or hold\$3)) same (semiconductor or semi\$conductor or wafer or disc or disk)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:11
S67	5094	(circumferential with (wall or surface or retain\$3 or hold\$3)) same (semiconductor or semi\$conductor or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:10
S66	8015	(circumferential with (wall or surface or retain\$3 or hold\$3)) same (semiconductor or semi\$conductor or wafer or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:10
S65	2	"5556275".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:10
S64	1220	134/153	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:08
S63	60487	(circumferential with (wall or surface or retain\$3 or hold\$3)) same (semiconductor or semi\$conductor or wafer or plate or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:07
S62	12	("20020036004" "20020166569" "5526835" "6340395" "6416647" "6681782").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 16:00

4/25/2008 11:24:04 AM

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